

## 4A, 650V N-CHANNEL MOSFET

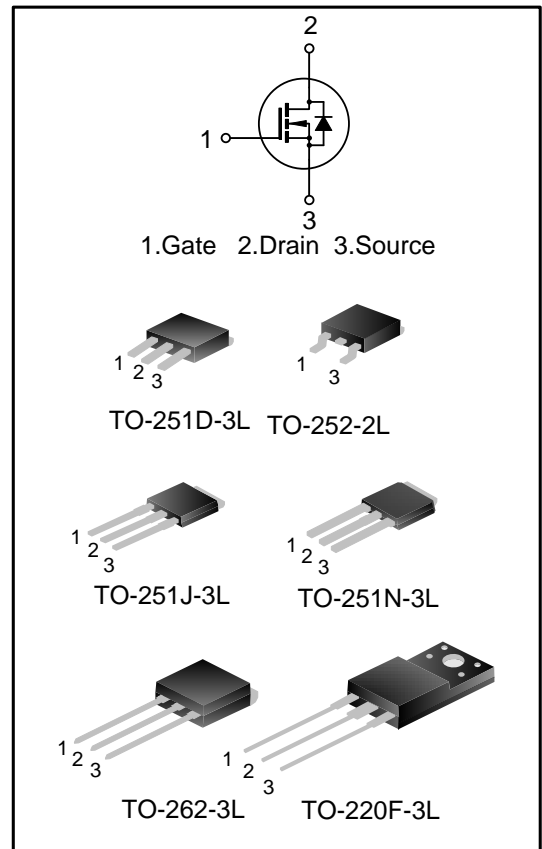
### GENERAL DESCRIPTION

SVF4N65CAF/D/M/MJ/MN/K is an N-channel enhancement mode power MOS field effect transistor which is produced using Silan proprietary F-Cell™ high-voltage planar VDMOS technology. The improved process and cell structure have been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are widely used in AC-DC power supplies, DC-DC converters and H-bridge PWM motor drivers.

### FEATURES

- ◆ 4A, 650V,  $R_{DS(on)(typ.)}=2.3\Omega@V_{GS}=10V$
- ◆ Low gate charge
- ◆ Low  $C_{rss}$
- ◆ Fast switching
- ◆ Improved dv/dt capability



### ORDERING INFORMATION

Part No.	Package	Marking	Hazardous Substance Control	Packing Type
SVF4N65CAF	TO-220F-3L	SVF4N65CAF	Halogen free	Tube
SVF4N65CADTR	TO-252-2L	4N65CAD	Halogen free	Tape & Reel
SVF4N65CAM	TO-251D-3L	4N65CAM	Halogen free	Tube
SVF4N65CAMJ	TO-251J-3L	4N65CAMJ	Halogen free	Tube
SVF4N65CAMN	TO-251N-3L	4N65CAMN	Halogen free	Tube
SVF4N65CAK	TO-262-3L	4N65CAK	Halogen free	Tube

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub>=25°C, UNLESS OTHERWISE NOTED)**

Characteristics	Symbol	Ratings				Unit
		SVF4N65 CAF	SVF4N65 CAM/D	SVF4N65 CAMJ/MN	SVF4N65 CAK	
Drain-Source Voltage	V <sub>DS</sub>	650				V
Gate-Source Voltage	V <sub>GS</sub>	±30				V
Drain Current	I <sub>D</sub>	T <sub>C</sub> =25°C				A
		T <sub>C</sub> =100°C				
Drain Current Pulsed	I <sub>DM</sub>	16				A
Power Dissipation(T <sub>C</sub> =25°C) -Derate above 25°C	P <sub>D</sub>	30	77	79	90	W
		0.24	0.62	0.63	0.72	W/°C
Single Pulsed Avalanche Energy (Note 1)	E <sub>AS</sub>	215				mJ
Operation Junction Temperature Range	T <sub>J</sub>	-55~+150				°C
Storage Temperature Range	T <sub>stg</sub>	-55~+150				°C

**THERMAL CHARACTERISTICS**

Characteristics	Symbol	Ratings				Unit
		SVF4N65 CAF	SVF4N65 CAM/D	SVF4N65 CAMJ/MN	SVF4N65 CAK	
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	4.17	1.62	1.58	1.39	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	62.5	62.0	62.0	62.5	°C/W

## ELECTRICAL CHARACTERISTICS (T<sub>J</sub>=25°C, UNLESS OTHERWISE NOTED)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain -Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	650	--	--	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =650V, V <sub>GS</sub> =0V	--	--	1.0	μA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	--	--	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> =250μA	2.0	--	4.0	V
Static Drain- Source On State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =2A	--	2.3	2.7	Ω
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz	--	430	--	pF
Output Capacitance	C <sub>oss</sub>		--	55	--	
Reverse Transfer Capacitance	C <sub>rss</sub>		--	4.1	--	
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =325V, V <sub>GS</sub> =10V, R <sub>G</sub> =25Ω, I <sub>D</sub> =4A (Note2,3)	--	9.9	--	ns
Turn-on Rise Time	t <sub>r</sub>		--	26	--	
Turn-off Delay Time	t <sub>d(off)</sub>		--	28	--	
Turn-off Fall Time	t <sub>f</sub>		--	26	--	
Total Gate Charge	Q <sub>g</sub>	V <sub>DD</sub> =520V, V <sub>GS</sub> =10V, I <sub>D</sub> =4A (Note 2,3)	--	13	--	nC
Gate-Source Charge	Q <sub>gs</sub>		--	2.7	--	
Gate-Drain Charge	Q <sub>gd</sub>		--	6.3	--	

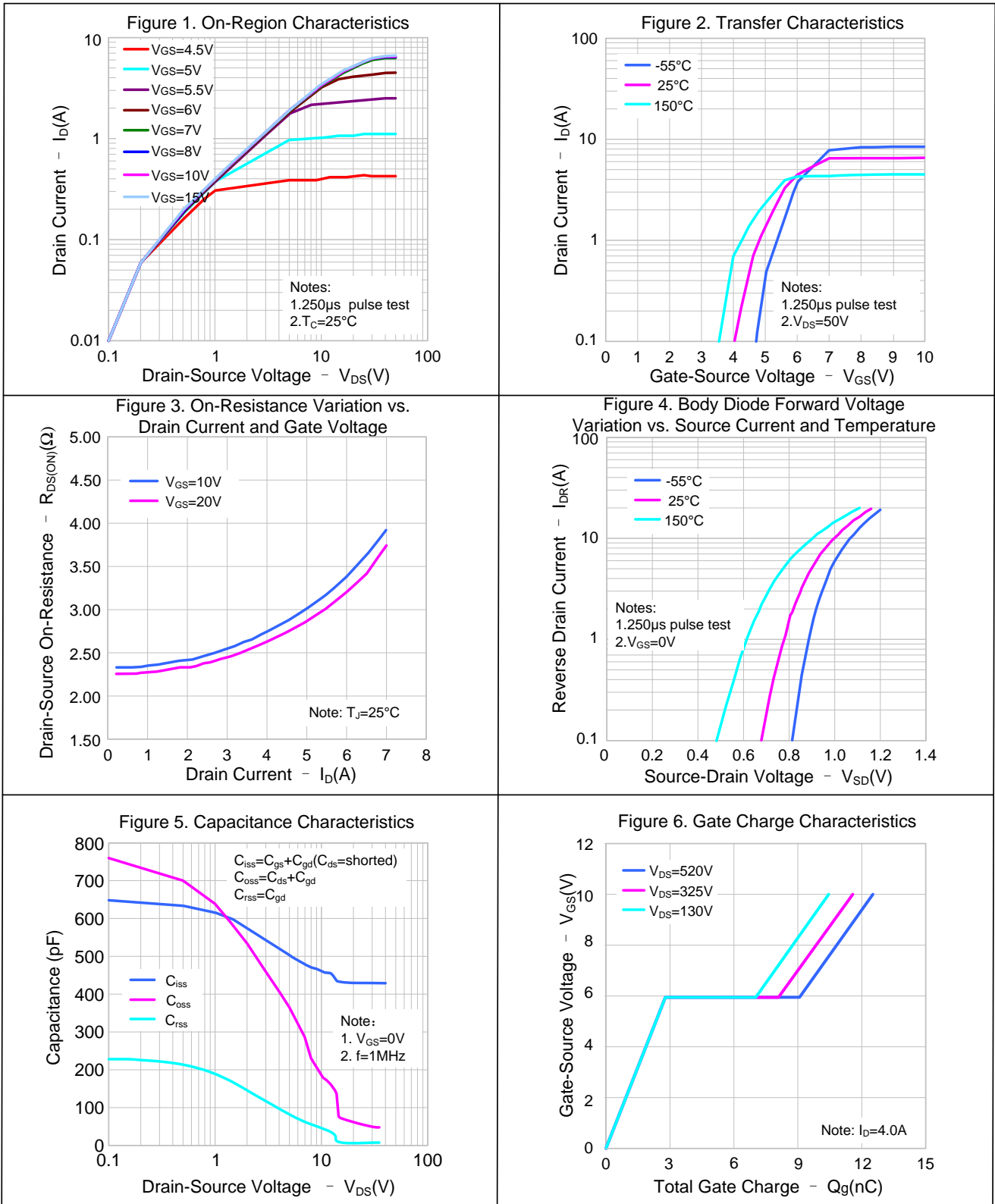
## SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I <sub>S</sub>	Integral Reverse P-N Junction Diode in the MOSFET	--	--	4.0	A
Pulsed Source Current	I <sub>SM</sub>		--	--	16	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =4.0A, V <sub>GS</sub> =0V	--	--	1.4	V
Reverse Recovery Time	T <sub>rr</sub>	I <sub>S</sub> =4.0A, V <sub>GS</sub> =0V,	--	450	--	ns
Reverse Recovery Charge	Q <sub>rr</sub>	dI <sub>F</sub> /dt=100A/μs (Note 2)	--	1.9	--	μC

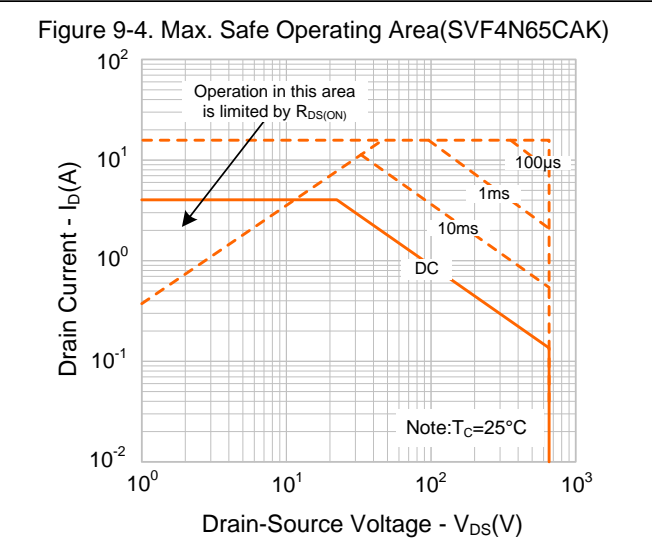
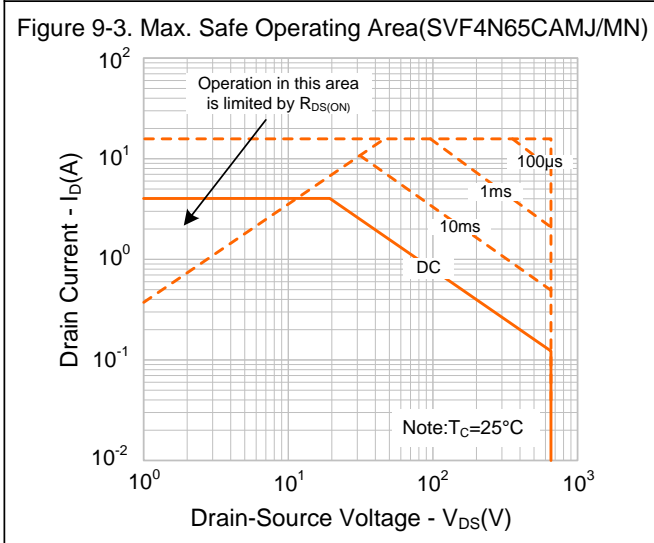
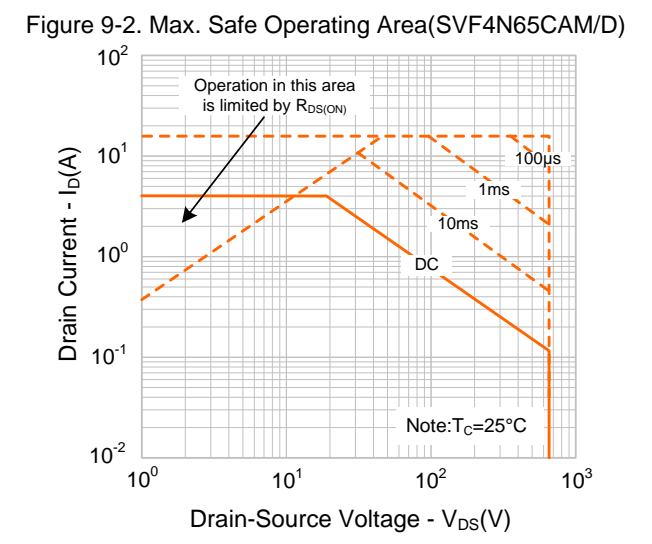
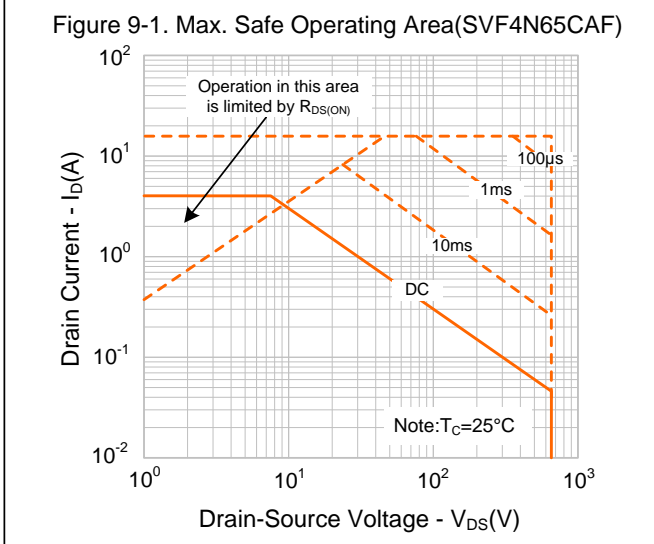
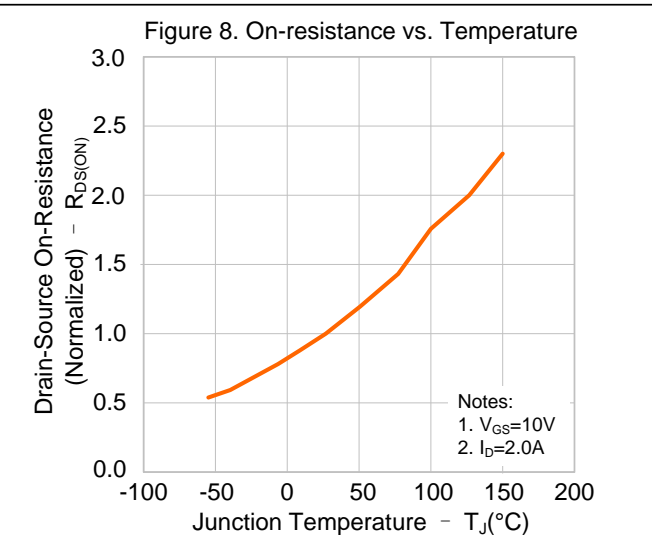
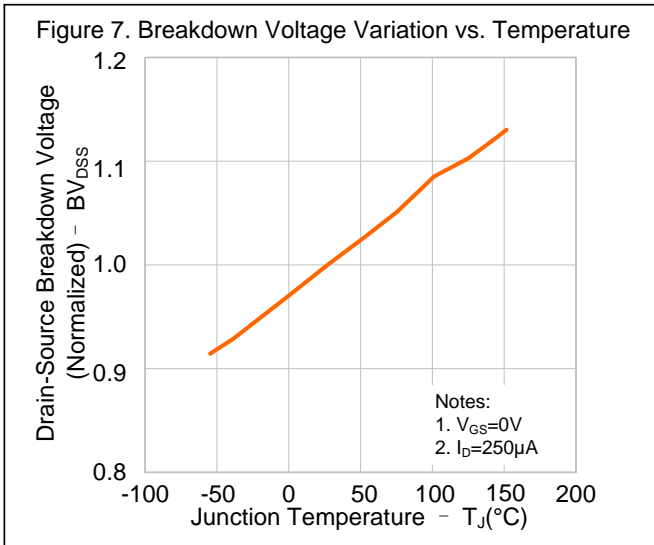
### Notes:

- L=30mH, I<sub>AS</sub>=3.6A, V<sub>DD</sub>=100V, R<sub>G</sub>=25Ω, starting T<sub>JB</sub>=25°C;
- Pulse Test: Pulse width ≤300μs, Duty cycle≤2%;
- Essentially independent of operating temperature.

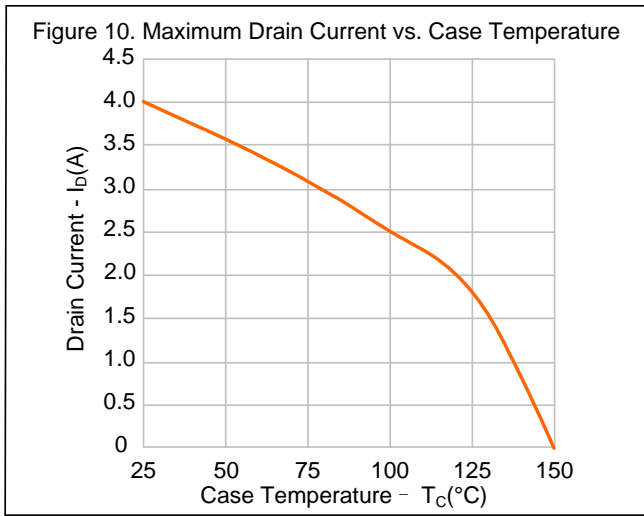
**TYPICAL CHARACTERISTICS**



**TYPICAL CHARACTERISTICS(CONTINUED)**

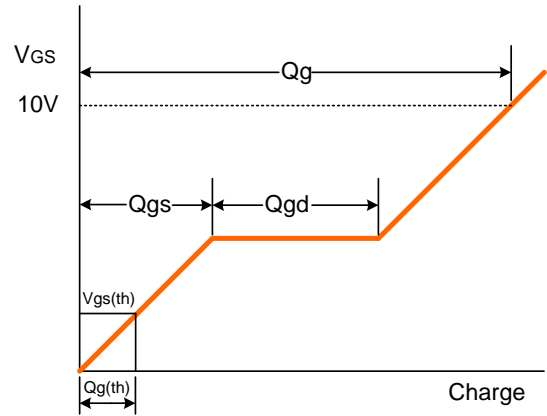
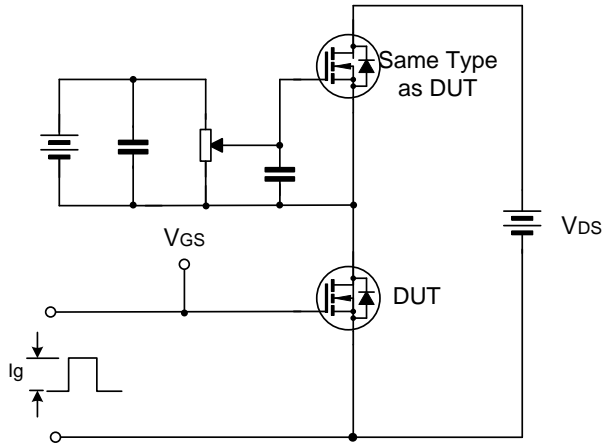


**TYPICAL CHARACTERISTICS(CONTINUED)**

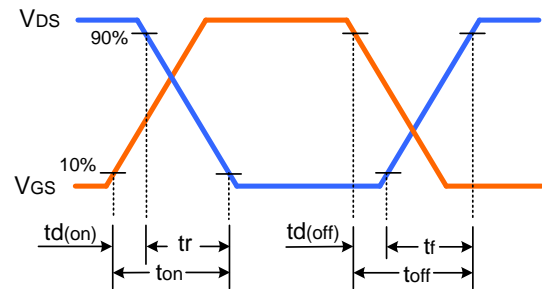
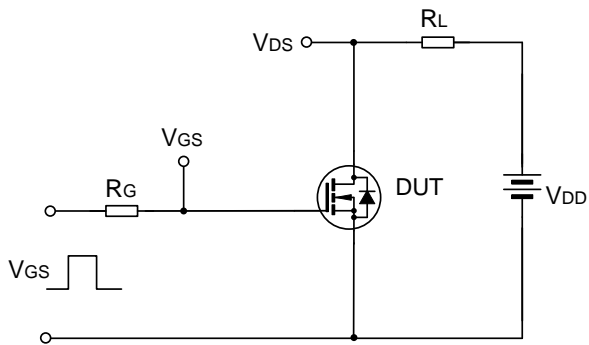


TYPICAL TEST CIRCUIT

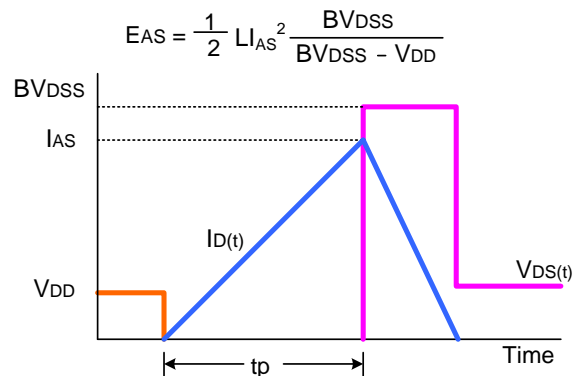
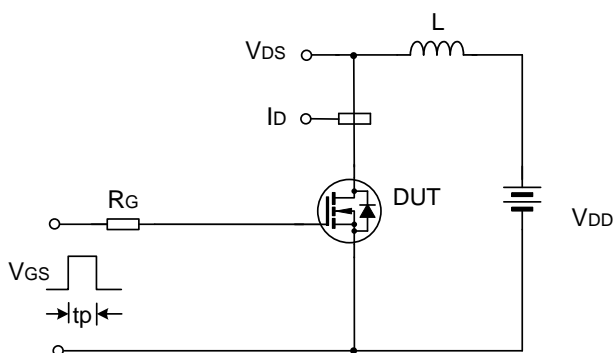
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



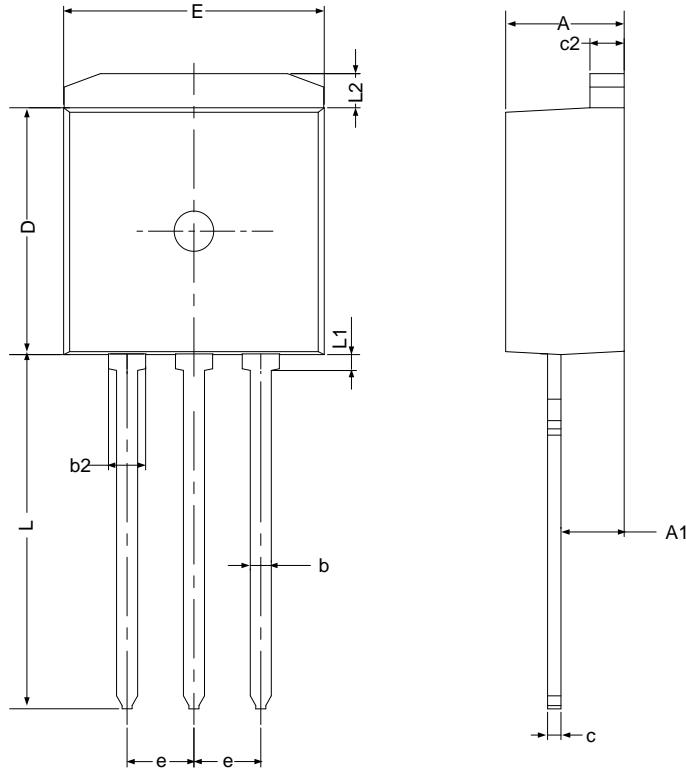
Unclamped Inductive Switching Test Circuit & Waveform



**PACKAGE OUTLINE**

**TO-262-3L**

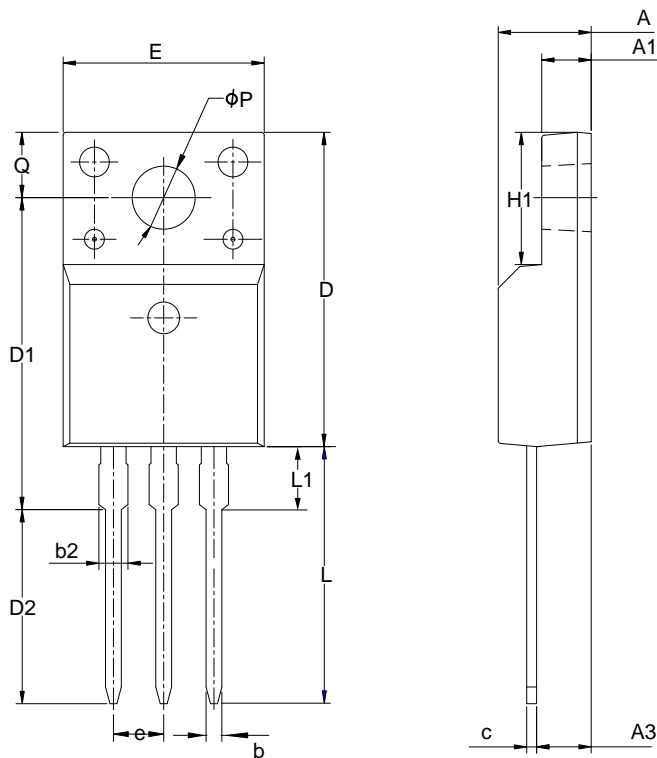
**UNIT: mm**



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.30	4.50	4.70
A1	2.20	—	2.92
b	0.71	0.80	0.90
b2	1.20	—	1.50
c	0.34	—	0.65
c2	1.22	1.30	1.35
D	8.38	—	9.30
E	9.80	10.16	10.54
e	2.54 BSC		
L	12.80	—	14.10
L1	—	—	0.75
L2	1.12	—	1.42

**TO-220F-3L**

**UNIT: mm**



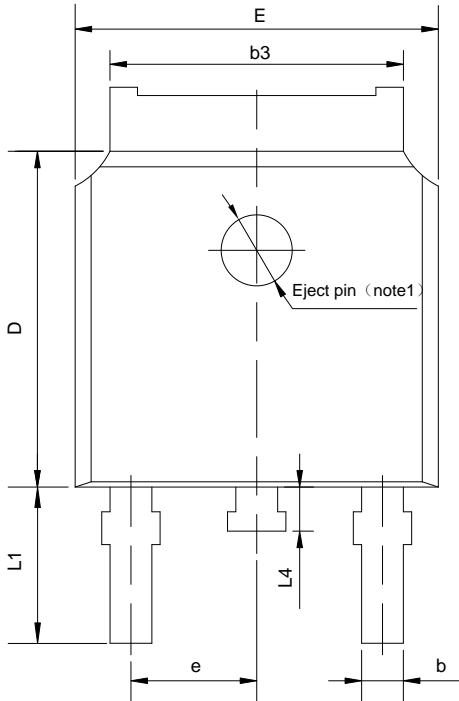
SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.42	4.70	5.02
A1	2.30	2.54	2.80
A3	2.50	2.76	3.10
b	0.70	0.80	0.90
b2	—	—	1.47
c	0.35	0.50	0.65
D	15.25	15.87	16.25
D1	15.30	15.75	16.30
D2	9.30	9.80	10.30
E	9.73	10.16	10.36
e	2.54BSC		
H1	6.40	6.68	7.00
L	12.48	12.98	13.48
L1	—	—	3.50
φP	3.00	3.18	3.40
Q	3.05	3.30	3.55



**PACKAGE OUTLINE(CONTINUED)**

**TO-252-2L**

**UNIT: mm**

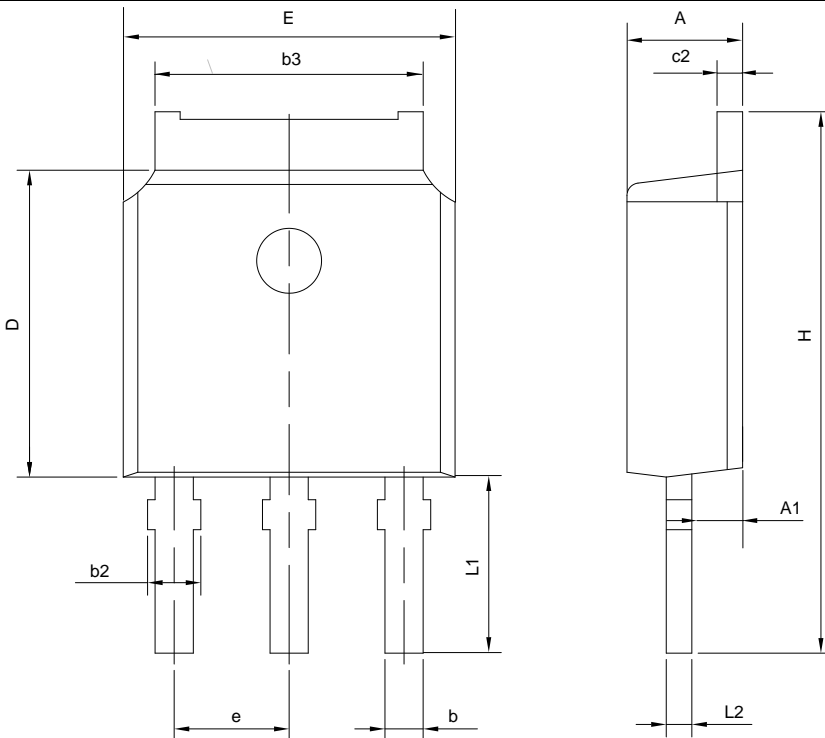


**NOTE1** : There are two conditions for this position:has an eject pin or has no eject pin.

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.10	2.30	2.50
A1	0	—	0.127
b	0.66	0.76	0.89
b3	5.10	5.33	5.46
c	0.45	—	0.65
c2	0.45	—	0.65
D	5.80	6.10	6.40
E	6.30	6.60	6.90
e	2.30TYP		
H	9.60	10.10	10.60
L	1.40	1.50	1.70
L1	2.90REF		
L4	0.60	0.80	1.00

**TO-251D-3L**

**UNIT: mm**

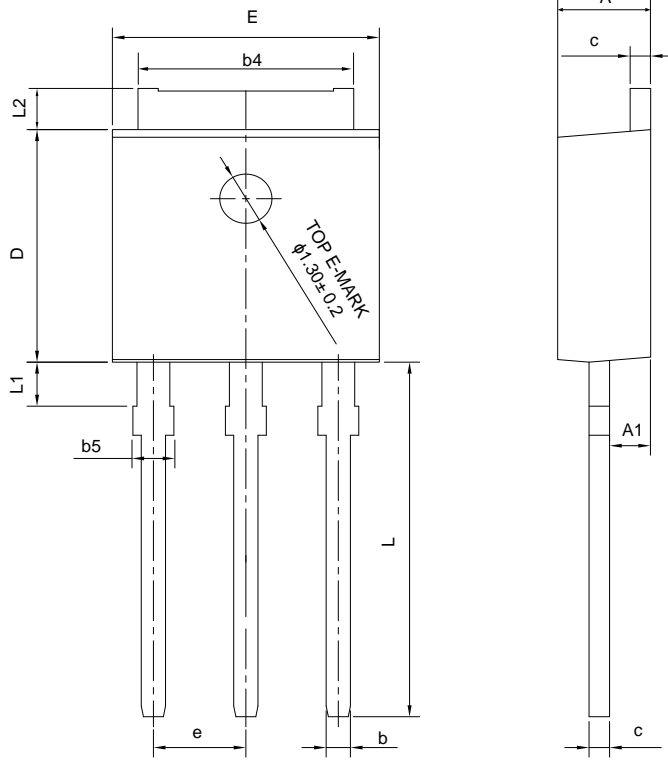


SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.20	2.30	2.40
b	0.66	—	0.86
b2	0.72	—	0.90
b3	5.10	5.33	5.46
c2	0.46	—	0.60
D	6.00	6.10	6.20
E	6.50	6.60	6.70
e	2.186	2.286	2.386
H	10.40	10.70	11.00
L1	3.50 REF		
L2	0.508 BSC		

**PACKAGE OUTLINE(CONTINUED)**

**TO-251J-3L**

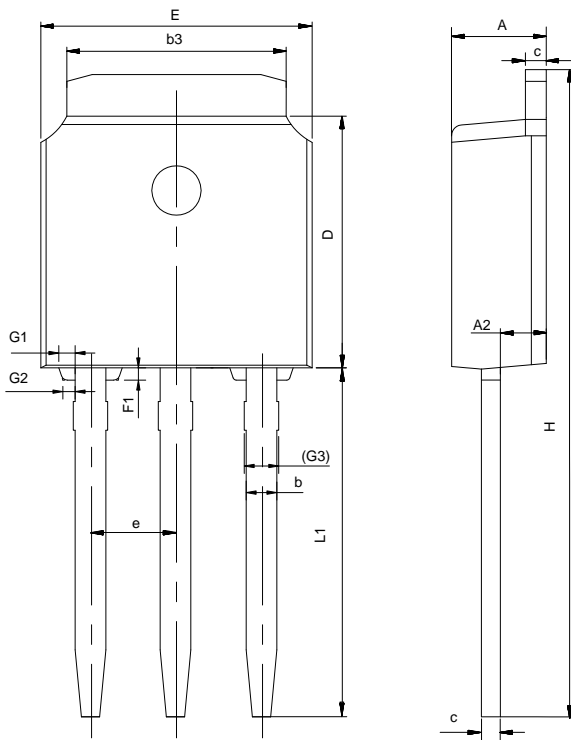
**UNIT: mm**



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.18	2.30	2.39
A1	0.89	1.00	1.14
b	0.56	—	0.89
b4	4.95	5.33	5.46
b5	—	—	1.05
c	0.46	—	0.61
D	5.97	6.10	6.27
E	6.35	6.60	6.73
e	2.29 BCS		
L	8.89	9.30	9.65
L1	0.95	—	1.50
L2	0.89	—	1.27

**TO-251N-3L**

**UNIT: mm**



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.20	2.30	2.40
A2	0.97	1.07	1.17
b	0.58	0.68	0.80
b3	5.20	5.33	5.50
c	0.43	0.53	0.63
D	5.80	6.10	6.40
E	6.30	6.60	6.90
e	2.286 BSC		
F1	0.20	0.30	0.40
G1	0.30	0.40	0.50
G2	0.20	0.30	0.40
G3	0.60	0.74	0.88
H	16.02	16.52	17.02
L1	9.10	9.40	9.70

**Important notice :**

1. The instructions are subject to change without notice!
2. Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current. Please read the instructions carefully before using our products, including the circuit operation precautions.
3. Our products are consumer electronic products or the other civil electronic products.
4. When using our products, please do not exceed the maximum rating of the products, otherwise the reliability of the whole machine will be affected. There is a certain possibility of failure or malfunction of any semiconductor product under specific conditions. The buyer is responsible for complying with safety standards and taking safety measures when using our products for system design, sample and whole machine manufacturing, so as to avoid potential failure risk that may cause personal injury or property loss.
5. It is strongly recommended to identify the trademark when buying our products. Please contact us if there is any question.
6. Product promotion is endless, our company will wholeheartedly provide customers with better products!
7. Website: <http://www.silan.com.cn>

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Rev.: 2.3

## Revision History:

1. Update electrical drawings and typical circuit diagrams
  2. Update important notice
- 

Rev.: 2.2

## Revision History:

1. Deleted NOMENCLATURE
  2. Modify Important notice
- 

Rev.: 2.1

## Revision History:

1. Delete the package outline of TO-262L-3L
- 

Rev.: 2.0

## Revision History:

1. Update package outline of TO-262-3L
- 

Rev.: 1.9

## Revision History:

1. Delete the package outline of TO-220F-3L(2)
  2. Update package outline of TO-251J-3L
- 

Rev.: 1.8

## Revision History:

1. Update Crss of Figure 5
  2. Update package outline of TO-251N-3L(1.1version)
- 

Rev.: 1.7

## Revision History:

1. Add the package of TO-262L-3L
- 

Rev.: 1.6

## Revision History:

1. Modify the Typical Characteristics

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Rev.: 1.5

Revision History:

1. Modify the typical characteristics

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Rev.: 1.4

Revision History:

1. Modify the package information of TO-220F-3L
  2. Modify the package information of TO-252-2L
- 

Rev.: 1.3

Revision History:

1. Add the package of TO-262-3L
  2. Modify the parameters
- 

Rev.: 1.2

Revision History:

1. Add the package of TO-251N-3L
- 

Rev.: 1.1

Revision History:

1. Modify the ordering information
  2. Modify the thermal characteristics
- 

Rev.: 1.0

Revision History:

1. First release
-